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Yamaki et al.

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(54) **ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING**

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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 451/66, 288, 289
CPC B24B 37/30; B24B 41/061; B24B 49/16
See application file for complete search history.

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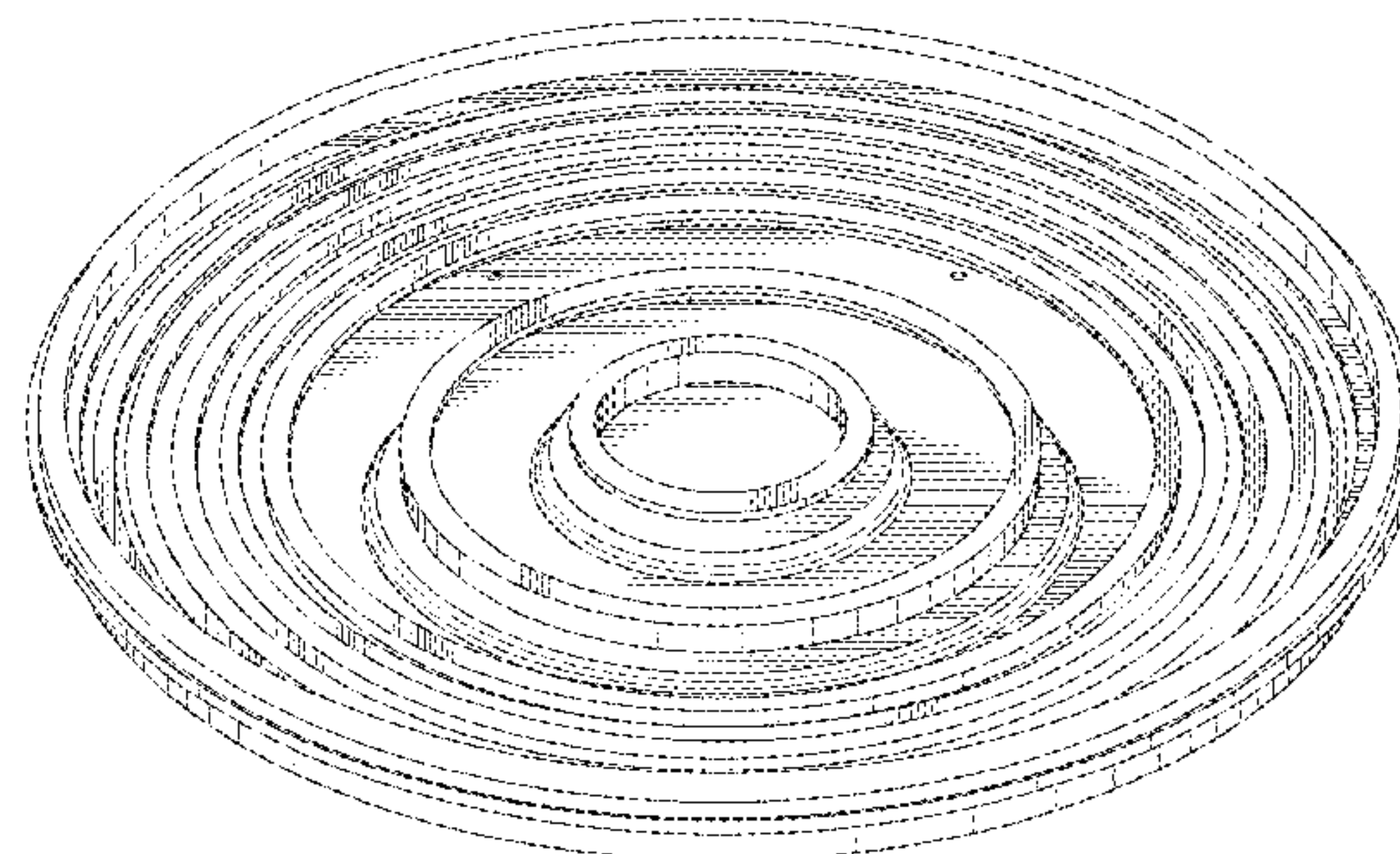
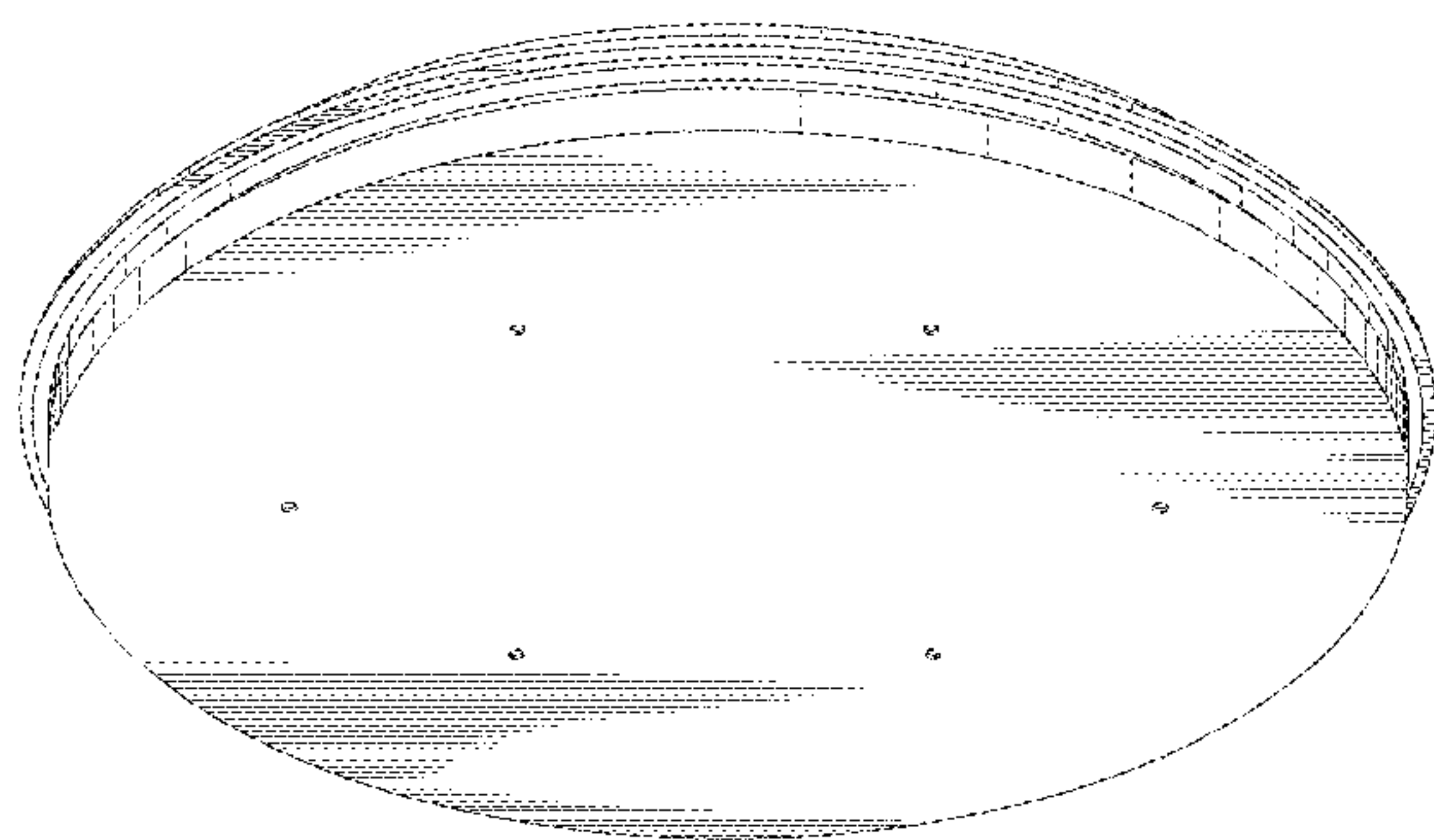
(57) **CLAIM**

The ornamental design for an elastic membrane for semiconductor wafer polishing, as shown and described.

DESCRIPTION

FIG. 1 is a bottom perspective view of an elastic membrane for semiconductor wafer polishing showing our new design; FIG. 2 is a top perspective view thereof; FIG. 3 is a bottom view thereof; FIG. 4 is a top view thereof; FIG. 5 is a front view thereof, a rear view being identical thereto; FIG. 6 is a right-side view thereof, a left-side view being identical thereto; FIG. 7 is a cross-sectional view taken along line 7-7 of FIG. 4; and, FIG. 8 is an enlarged portion view labeled FIG. 8 in FIG. 7. The dash-dot lines in FIG. 7 represent the boundary line of the enlarged portion view shown in FIG. 8.

1 Claim, 6 Drawing Sheets



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FIG. 1

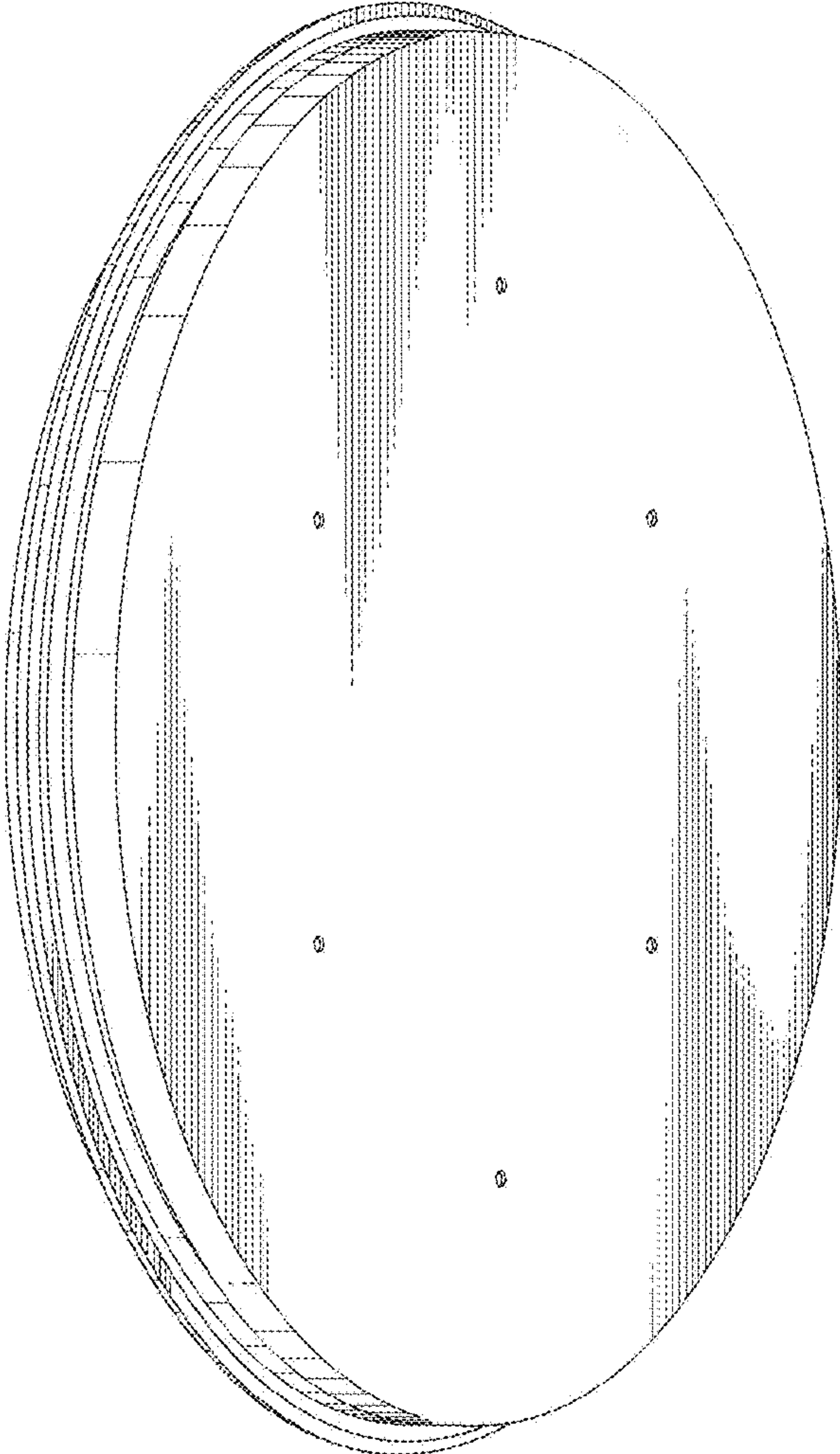


FIG. 2

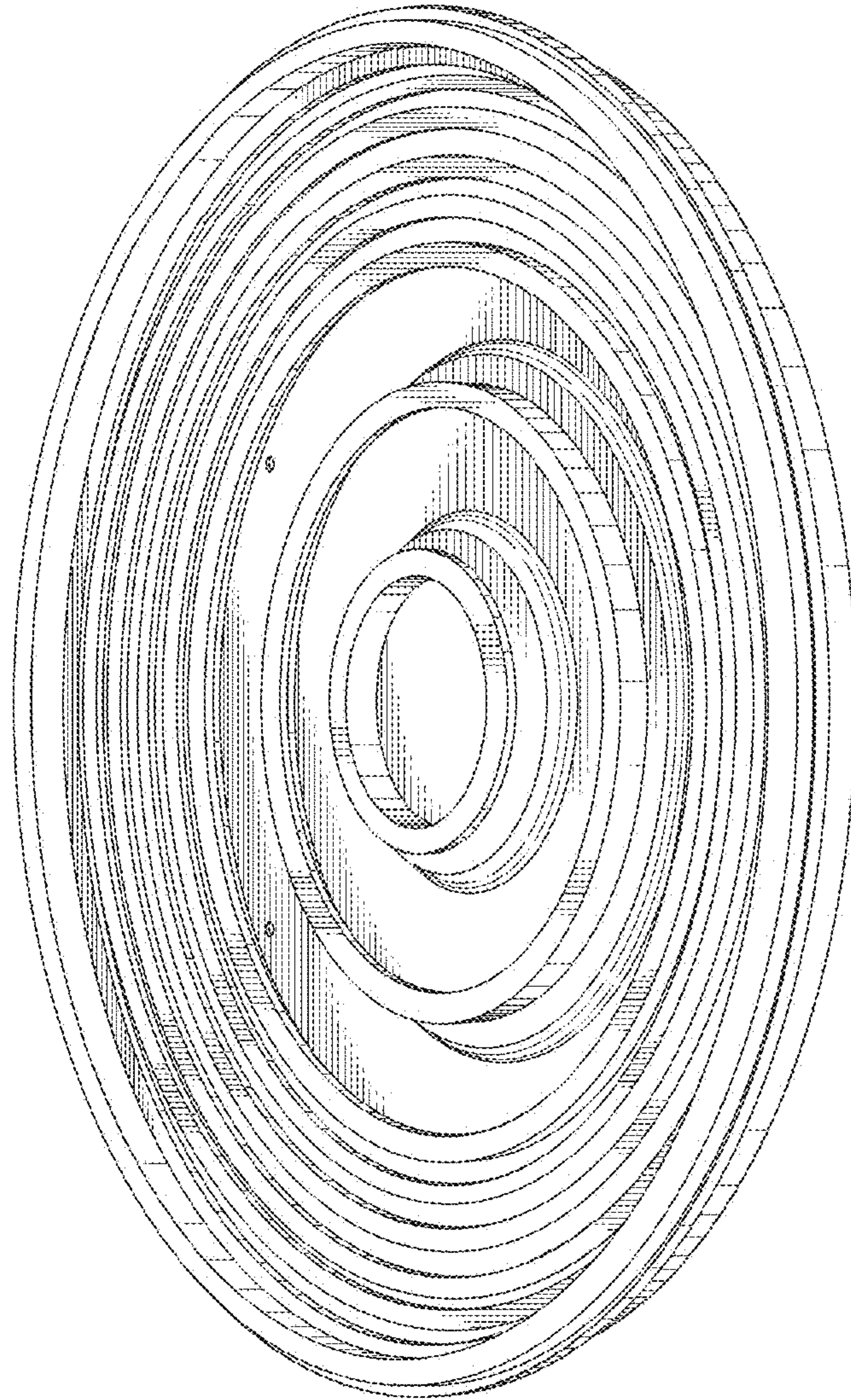


FIG. 3

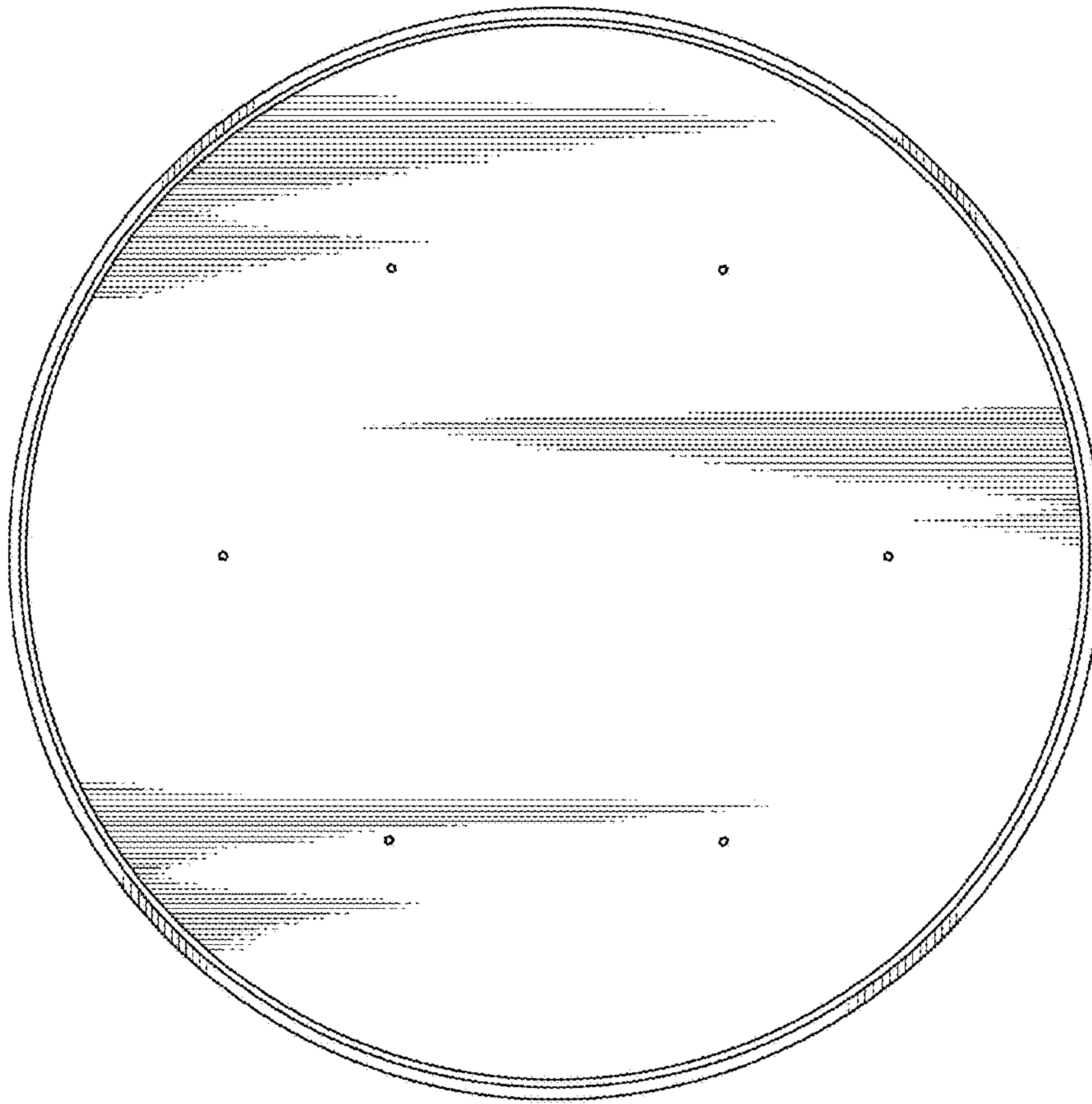


FIG. 4

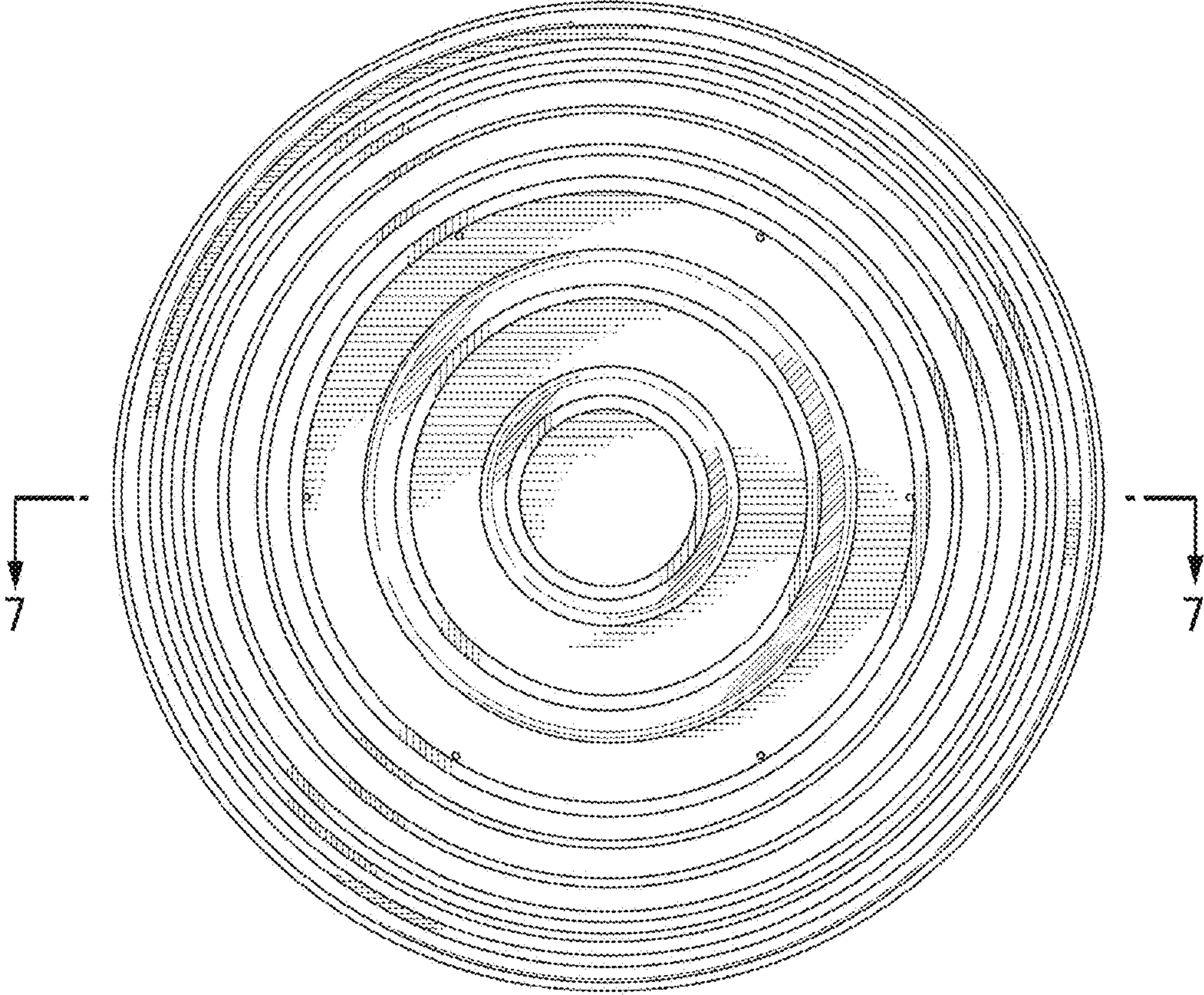


FIG. 5



FIG. 6



FIG. 7

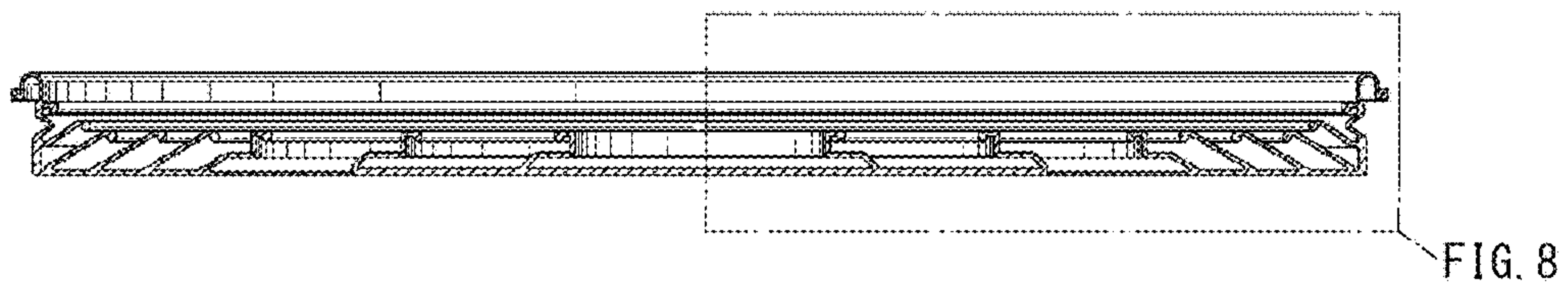


FIG. 8

